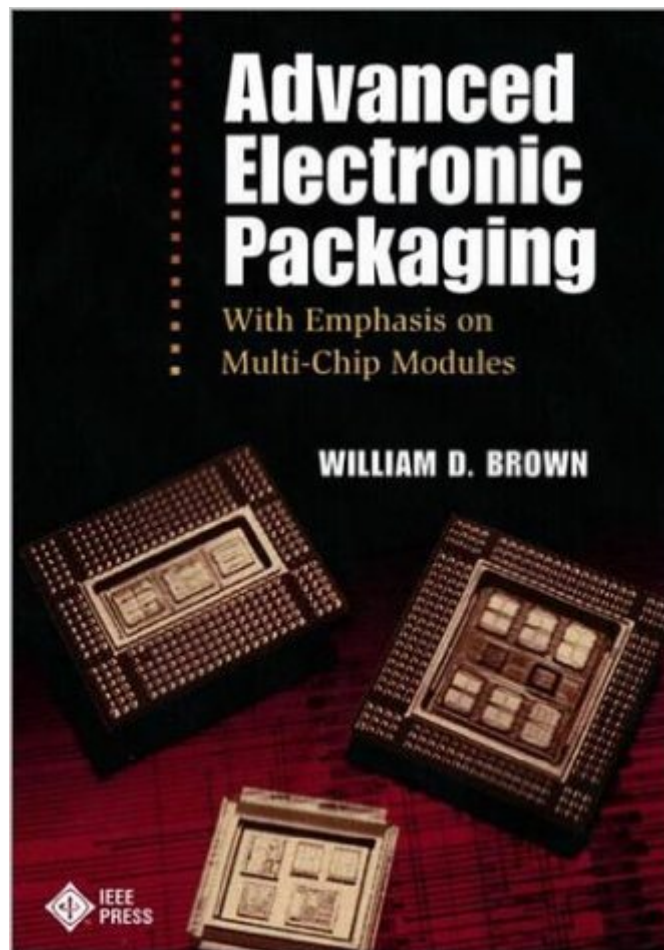


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# Advanced Electronic Packaging: With Emphasis On Multichip Modules (IEEE Press Series On Microelectronic Systems)



## Synopsis

Packaging is rapidly becoming an area of microelectronics technology which can limit the operating speed on an integrated circuit. To address this concern, much research and development attention now focuses on packaging in an effort to prevent it from impeding the speed of electronic systems. With *Advanced Electronic Packaging*, readers can learn about the full range of packaging concepts, from the introductory to the advanced level, and gain a deeper understanding of this rapidly growing area of microelectronics. As an excellent desk reference for practicing engineers or as an ideal text for students in interdisciplinary engineering classes, this comprehensive book discusses all aspects of the sciences and technologies involved in the fabrication, testing, reliability, and packaging of integrated circuits, specifically, multichip modules (MCM). In addition, you will find industrial case studies for several MCM technologies along with an assessment of design tradeoffs. Also addressed are the critical role of economics and future trends in electronic packaging. An Instructor's Manual presenting detailed solutions to all the problems in the book is available upon request from the Wiley Marketing Department.

## Book Information

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## Customer Reviews

I am a student of Dr. Brown. I must emphasize that the book that he has edited and a part of which he has written, is just excellent in its quality and quantity. By quality I mean its the best book on

packaging that I have read and by quantity I mean the book has something on everything. Most of the books are like a lot on a topic and very less on most of the other topics, but this book surpasses everything. It treats every chapter fairly and equally. The book will not make one an expert in packaging, but would surely make one feel satisfied with the content and knowledge. I hope that other readers too would find this book good and informative.

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